

SDB1040HP

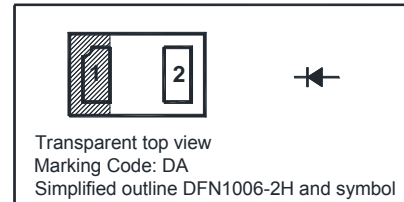
SCHOTTKY BARRIER DIODE

Features

- Low forward voltage drop

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode

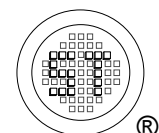


Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

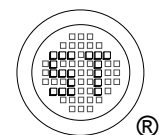
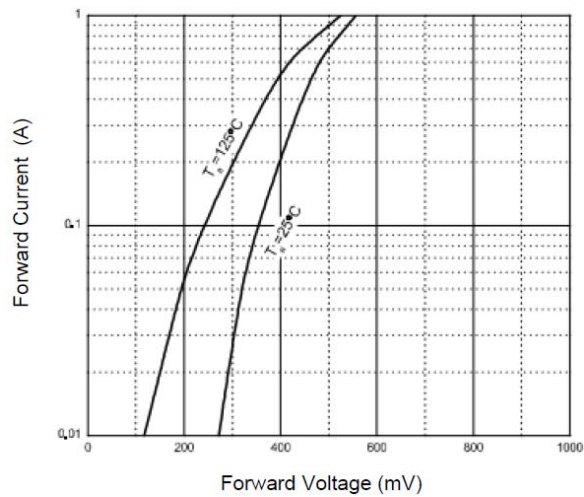
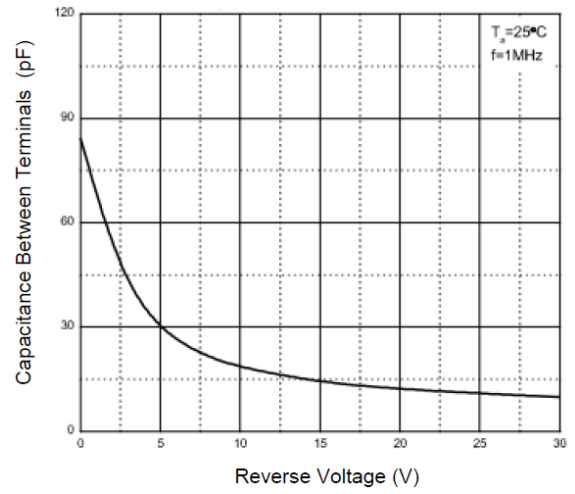
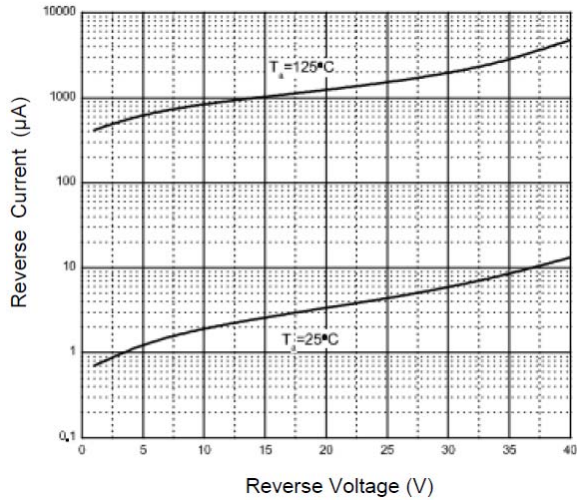
Parameter	Symbol	Value	Unit
Reverse Voltage	V_R	40	V
RMS Voltage	V_{RMS}	28	V
Average Forward Current	I_O	1	A
Non-repetitive Peak Forward Surge Current	I_{FSM}	7	A
Power Dissipation	P_D	500	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	250	$^\circ\text{C/W}$
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 55 to + 150	$^\circ\text{C}$

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Unit
Reverse Breakdown Voltage at $I_R = 1\text{ mA}$	$V_{(BR)R}$	40	-	-	V
Forward Voltage at $I_F = 0.1\text{ A}$ at $I_F = 0.2\text{ A}$ at $I_F = 0.5\text{ A}$ at $I_F = 0.7\text{ A}$ at $I_F = 1\text{ A}$	V_F	- - - - -	- - - - -	0.38 0.4 0.49 0.55 0.61	V
Reverse Current at $V_R = 40\text{ V}$	I_R	-	-	40	μA
Capacitance Between Terminals at $V_R = 0\text{ V}$, $f = 1\text{ MHz}$	C_T	-	19	-	pF



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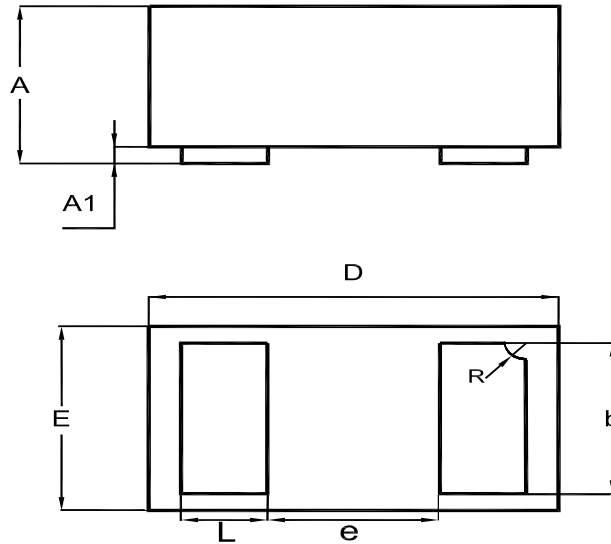


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PACKAGE OUTLINE

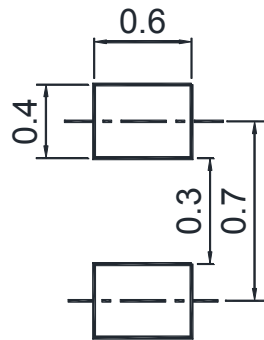
Plastic surface mounted package

DFN1006-2H



UNIT	A	A1	b	D	E	e	L	R
mm	0.51 0.46	0.05 0	0.55 0.45	1.05 0.95	0.65 0.55	0.4	0.3 0.2	0.15 0.05

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1006-2H	8	4 ± 0.1	0.157 ± 0.004	178	7	5,000

